TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $\pi$ -MOSV)

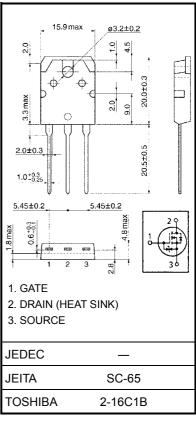
# 2SK2602

#### Switching Regulator Applications

- Low drain-source ON resistance  $R_{DS}(ON) = 0.9 \Omega$  (typ.)
- High forward transfer admittance  $|Y_{fs}| = 5.5 \text{ S (typ.)}$
- Low leakage current  $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 600 \ V)$
- Enhancement-mode  $: V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

#### Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V <sub>DSS</sub>	600	V
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	600	V
Gate-source voltage		V <sub>GSS</sub>	±30	V
Drain current	DC (Note 1)	۱ <sub>D</sub>	6	А
	Pulse (Note 1)	I <sub>DP</sub>	24	А
Drain power dissipatio	n (Tc = 25°C)	PD	125	W
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	345	mJ
Avalanche current		I <sub>AR</sub>	6	А
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	12.5	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature r	ange	T <sub>stg</sub>	-55~150	°C



Weight: 4.6 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch−c)</sub>	1.0	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	50	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 16.8 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 6 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.

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Unit: mm

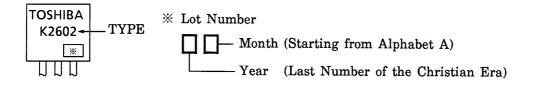
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I <sub>GSS</sub>	$V_{GS}$ = ±25 V, $V_{DS}$ = 0 V	_		±10	μA
Gate-source bro	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	_	-	100	μA
Drain-source br	eakdown voltage	I (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	V
Gate threshold v	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0		4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A,		0.9	1.25	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	2.0	5.5	_	S
Input capacitance Reverse transfer capacitance		C <sub>iss</sub>			1300	_	pF
		C <sub>rss</sub>			130	_	
Output capacitance		C <sub>oss</sub>			400	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \prod_{O \\ O \\$		25	_	
	Turn-on time	t <sub>on</sub>		_	45	_	20
	Fall time	t <sub>f</sub>		_	40	_	- ns
	Turn-off time	t <sub>off</sub>		_	150	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	30	_	
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A		18	—	nC
Gate-drain ("miller") Charge		Q <sub>gd</sub>			12	_	

## Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	6	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	—	_	_	24	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 100 A / μs	—	1000		ns
Reverse recovery charge	Q <sub>rr</sub>	$1DR = 0 A$ , $VGS = 0 V$ , $0DR / 01 = 100 A / \mu s$	—	7		μC

## Marking

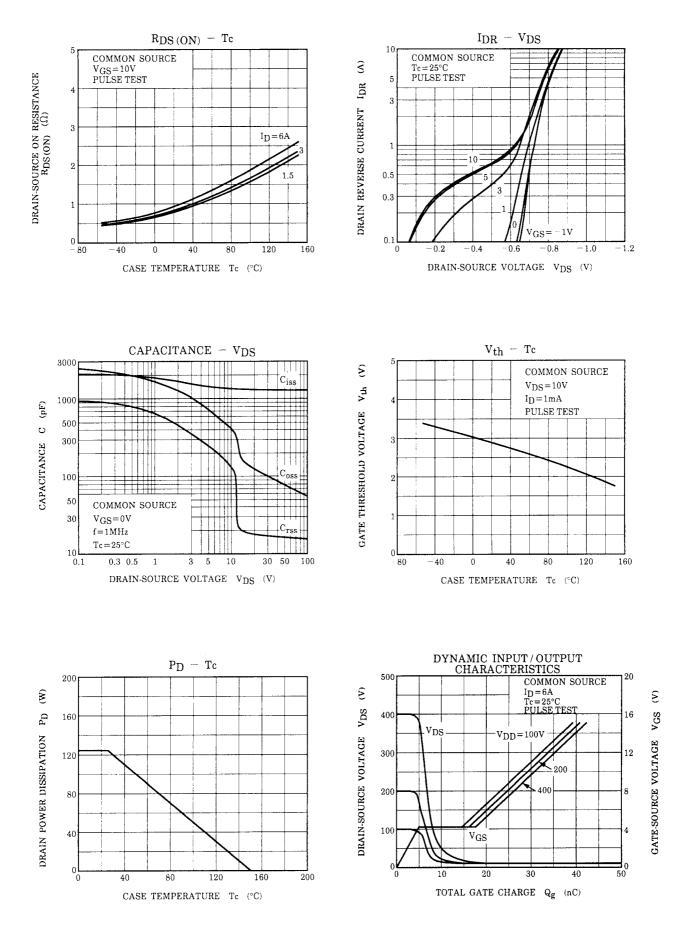


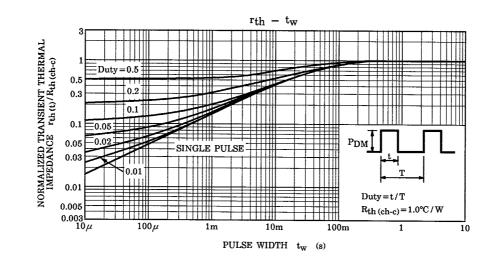
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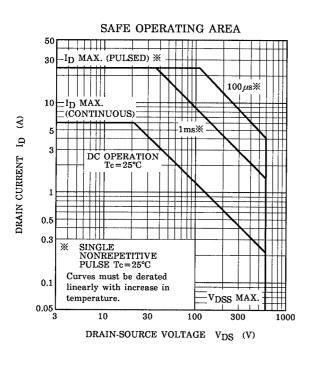
 $I_D\ -\ V_{DS}$  $I_D - V_{DS}$ 10 E 10, 15 COMMON SOURCE 10 4.8 COMMON Tc=25°C PULSE TEST 5.2 SOURCE 15 $Tc = 25^{\circ}C$ 5 4.6 Ý ર્ક PULSE TEST ŋ ŋ 4.8 DRAIN CURRENT 3 DRAIN CURRENT 4.4 4.6 2 4.2 4.4  $V_{GS} = 4V$ 4.2 $V_{GS} = 4V$ 0 0 10 20 30 40 50 10 2 4 6 8 0 0 DRAIN-SOURCE VOLTAGE VDS (V) DRAIN-SOURCE VOLTAGE VDS (V)  $I_D - V_{GS}$  $V_{DS} - V_{GS}$ 10 10 COMMON SOURCE Tc=25°C PULSE TEST S  $v_{DS}$ Ś DRAIN CURRENT ID DRAIN-SOURCE VOLTAGE  $I_D = 6A$ 6 100 25 $Tc = -55^{\circ}C$ 1.5 COMMON SOURCE V<sub>DS</sub>=20V PULSE TEST 0L 0L 16 12 20 2 10 4 8 GATE-SOURCE VOLTAGE  $V_{GS}$  (V) GATE-SOURCE VOLTAGE VGS (V)  $|Y_{fs}| - I_D$  $R_{DS(ON)} - I_D$ COMMON SOURCE COMMON SOURCE FORWARD TRANSFER ADMITTANCE |Y<sub>fs</sub>| (S) V<sub>DS</sub>=20V PULSE TEST Tc = --55°C  $Tc = 25^{\circ}C$ DRAIN-SOURCE ON RESISTANCE RDS ( $\Omega$ ) ( $\Omega$ ) 10 25PULSE TEST 100  $V_{GS} = 10, 15V$ 5 3 0.5 0.3 ++0.5 0.1L 0.1 0.3 0.5 10 5 3 0.1 0.3 0.5 3 5 10 1 1 DRAIN CURRENT  $I_D$  (A) DRAIN CURRENT ID (A)

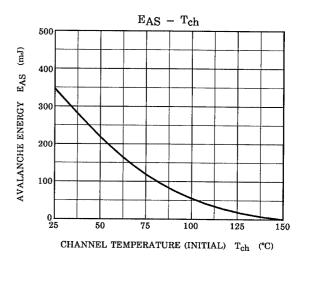
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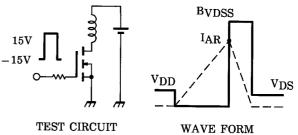
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